

AN 1999:518599 HCAPLUS
 DN 131:192795
 TI Mounted structure containing lead-free solders and packaging method of
 electronic parts using it
 IN Nakatsuka, Tetsuya; Ishida, Toshiharu; Soga, Tasao
 PA Hitachi, Ltd., Japan
 SO Jpn. Kokai Tokkyo Koho, 12 pp.
 CODEN: JKXXAF
 DT Patent
 LA Japanese
 FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 11221694	A2	19990817	JP 1998-25998	19980206
AB	<p>The title structure comprises an org. substrate mounted with electronic parts on both sides by using Sn alloy solders contg. Bi 0-65, Ag 0.5-4.0, and Cu and/or In (as total) 0-3.0 mass%. Also claimed structure uses (A) a Pb-free solder for the 1st surface and (B) a Pb-free solder for the 2nd surface, where solid-phase line temp. of A is higher than liq.-phase line temp. of B. Claimed method comprises reflow soldering by using the above solders. The solders show good wettability and adhesion strength.</p>				